Display Elektronik GmbH

DATA SHEET

TFT MODULE

DEM 240320C TMH-PW-N

2,6" TFT

Product Specification

Ver.: 0

11.02.2011

Revise Records

Rev.	Date	Contents	Written	Approved
0	11.02.2011	Preliminary Specification	CL	MH

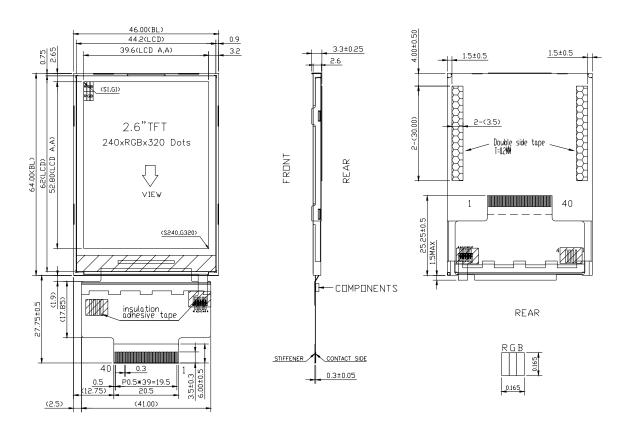
Special Notes

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1. LCM DRAWING



2. GENERAL DESCRIPTION

MAIN TECHNICS: TFT, Negative Transmissive

DISPLAY CONTENT: 240 x RGB x 320, GRAPHIC

DISPLAY TYPE: 262k

DRIVER METHOD: 1/320 DUTY

VIEWING DIRECTION: 12:00

CONTROLLER: R61580 (Renesas)

BACKLIGHT: LED, Lightguide, White

OPERATING TEMPERATURE: -20°C to +70°C

STORAGE TEMPERATURE: -30°C to +80°C

INTERFACE: SPI and 8080 Series MPU, 8/16-bit

REFERENCE DOCUMENTS: R61580 datasheet

3. MECHANICAL SPECIFICATIONS

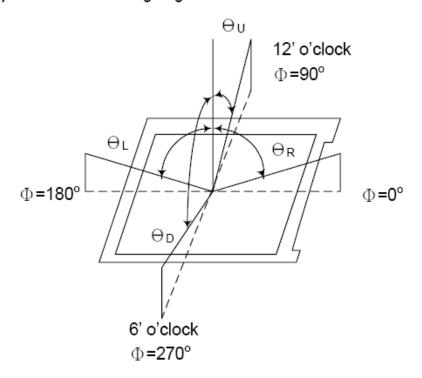
ITEM	CONTENT	UNIT
NUMBER OF PIXELS	240 x RGB x 320	PIXEL
MODULE DIMENSION	46.00 x 91.75 x 3.30	mm
ACTIVE AREA	39.60 x 52.80	mm
PIXEL SIZE	0.165 x 0.165	mm

4. ELECTRO-OPTICAL CHARACTERISTICS

Item		Symbol	Condition	Min.	Тур.	Max.	Unit	Note	
Transmittand (without Pola		T(%)	_	_	14.7	_	_		
Contrast Rat	io	CR	⊖=0	400	500	_	_	(1)(2)	
	Rising	T _R	Normal	_	2	4			
Response time	Falling	T _F	viewing angle —		6	12	msec	(1)(3)	
Color gamut		S(%)			60		%		
	White	W _x		0.288	0.308	0.328			
	vvnite	Wy		0.305	0.325	0.345			
	Red	Rx		0.610	0.630	0.650			
Color	Reu	Ry		0.317	0.337	0.357		(1)(4)	
chromaticity	Green	Gx		0.264	0.284	0.304		CF glass	
(CIE1931)	Green	Gy		0.523	0.543	0.563		(C-light)	
	Blue	Bx		0.123	0.143	0.163			
	Diue	Ву		0.100	0.120	0.140			
	Llaw	θL		35	45	_			
Viewing	Hor.	Θ_{R}	CB>10	35	45	_			
angle	Var	θυ	CR>10	35	45	_			
	Ver.	θD		10	20	_			
Optima View Direction	,		12 O'clock						

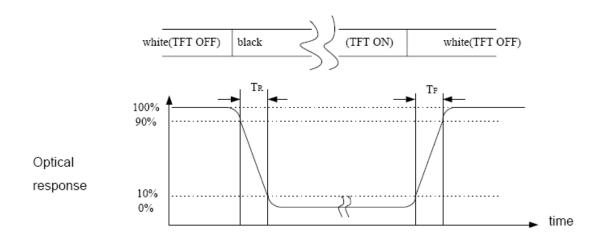
Measuring Equipment

Note (1) Definition of Viewing Angle:

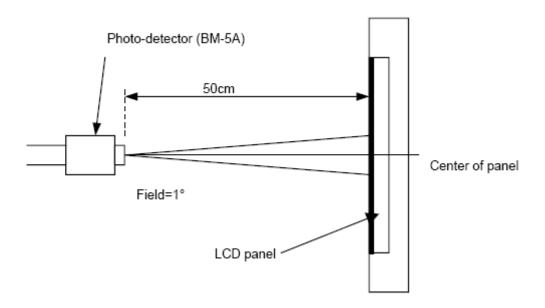


Note (2) Definition of Contrast Ratio(CR): measured at the center point of panel

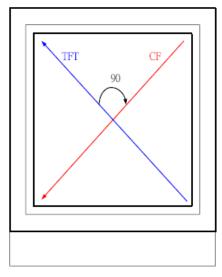
Note (3) Definition of Response Time : Sum of $T_{\mbox{\tiny R}}$ and $T_{\mbox{\tiny F}}$



Note (4) Definition of optical measurement setup

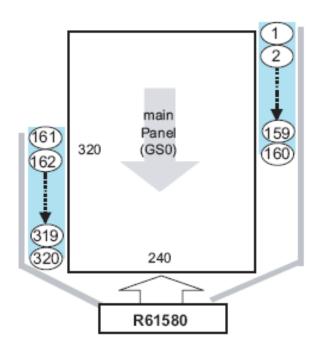


Note (5) Rubbing Direction (The different Rubbing Direction will cause the different optima view direction.



TFT Face up

5. BLOCK DIAGRAM



6. ELECTRONIC CHARACTERISTICS

6.1 MAXIMUM VALUES

	CYMIDOI	STANDARD	VALUE	TINITO
ITEM	SYMBOL	MIN	MAX	UNIT
Logic supply voltage	V_{DD}	-0.3	+4.6	V
Operating Temperature	Top	-20	+70	°C
Storage Temperature	Tst	-30	+80	°C

6.2 DC CHARACTERISTICS

DC Characteristics 1 (VCC= 2.50V~3.30V, IOVCC=1.65V~3.30V, Ta=-40C~+85C)

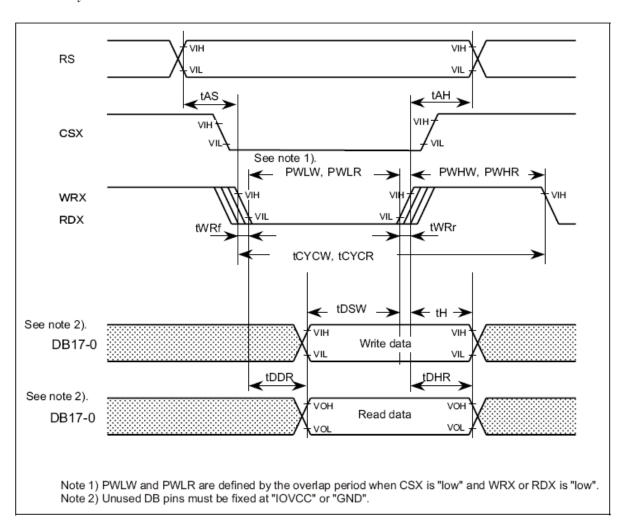
Item	Symbol	Unit	Test Condition	Min.	Тур.	Max.	Note
Input "High" level voltage 1 Except RESETX pin	V _{IH1}	٧	IOVCC=1.65V~3.30V	0.80× IOVCC	_	IOVCC	2, 3
Input "Low" level voltage 1 Except RESETX pin	V _{IL1}	٧	IOVCC=1.65V~3.30V	-0.3	_	0.20× IOVCC	2, 3
Input "High" level voltage 2 RESETX pin	V _{IH2}	٧	IOVCC=1.65V~3.30V	0.90× IOVCC	_	IOVCC	2, 3
Input "Low" level voltage 2 RESETX pin	V _{IL2}	٧	IOVCC=1.65V~3.30V	-0.3	_	0.10× IOVCC	2, 3
Output "High" level voltage 1 (DB0-17, FMARK)	V _{OH}	٧	IOVCC=1.65V~3.30V, IOH=-0.1mA	0.8× IOVCC	_	_	2
Output "Low" level voltage 1 (DB0-17, FMARK)	V _{OL}	٧	IOVCC=1.65V~3.30V, IOL=0.1mA	_	_	0.20× IOVCC	2
Input/Output leakage current	ILI	μΑ	Vin=0∼IOVCC	-1	_	1	4
Current consumption ((IOVCC-GND) + (VCC-GND)) Normal operation (260-k color, display operation)	I _{OP1}	MA	fosc=678kHz (320 line drive), IOVCC=VCC=3.00V, fFLM=70Hz, Ta=25°C, Frame memory data: 18'h000000, BLCON=0, See below for other information	_	0.6	TBD	5
Current consumption ((IOVCC-GND) + (VCC-GND)) Normal operation (260-k color, display operation), BLC ON	I _{OP1}	mA	fosc=678kHz (320 line drive), IOVCC=VCC=3.00V, fFLM=70Hz, Ta=25°C, Frame memory data: 18'h000000, BLCON=1, See below for other information	_	0.8	TBD	5
Current consumption ((IOVCC-GND) + (VCC-GND)) 8-color mode (64 line partial display operation)	I _{op2}	μA	fosc=678kHz (64 line partial display operation), IOVCC=VCC=3.00V, fFLM=40Hz, Ta=25°C, Frame memory data: 18h'000000, BLCON=0, See below for other information	_	140	_	5
Current consumption ((IOVCC-GND) + (VCC-GND)) Deep standby mode	I _{DST}	μA	IOVCC=VCC=3.00V, Ta=25°C	_	0.1	TBD	5

DC Characteristics 2: Step-up circuit characteristics

Item		Unit	Test condition	Min.	Тур.	Max.	Note
	DD∨DH	V	IOVCC=VCC=2.8V, VCI =2.8V, Ta=25°C, VC=3'h1, BT=3'h4, AP=2'h3, DC0=3'h3, DC1=3'h2, C11=C12=C13=C21=C22=1[uF]/B characteristics, DDVDH=VGH=VGL=VCL=1[uF]/B characteristics, No load on the panel, Iload1=-3 [mA]	4.8	5.1	-	
Step-up	VGH	V	IOVCC=VCC=2.8V, VCI =2.8V, Ta=25°C, VC=3°h1, BT=3°h4, AP=2°h3, DC0=3°h3, DC1=3°h2, C11=C12=C13=C21=C22=1[uF]/B characteristics, DDVDH=VGH=VGL=VCL=1[uF]/B characteristics, Iload2=-100[uA], No load on the panel	14.4	15.1	-	
voltage	VGL	V	IOVCC=VCC=2.8V, VCI =2.8V, Ta=25°C, VC=3°h1, BT=3°h4, AP=2°h3, DC0=3°h3, DC1=3°h2, C11=C12=C13=C21=C22=1[uF]/B characteristics, DDVDH=VGH=VGL=VCL=1[uF]/B characteristics, Iload3=+100[uA], No load on the panel	-	-10.0	-9.6	
	VCL	V	IOVCC=VCC=2.8V, VCI =2.8V, Ta=25°C, VC=3°h1, BT=3°h4, AP=2°h3, DC0=3°h3, DC1=3°h2, C11=C12=C13=C21=C22=1[uFJ/B characteristics, DDVDH=VGH=VGL=VCL=1[uFJ/B characteristics, Iload4=+200[uA], No load on the panel	-	-2.55	-2.4	

6.3 TIMING CHARACTERISTICS

80-System Bus Interface



80-System Bus Interface Timing Characteristics (9-/8-bit Interface)

Table 104 (IOVCC= $1.65V \sim 3.30V$) (T.B.D.)

ltem		Symbol	Unit	Timing Diagram	Min.	Тур.	Max.
Bus cycle time	Write	tcycw	ns	Figure A	70	_	_
	Read	tcycr	ns	Figure A	450	_	_
Write low-level po	ulse width	PWLw	ns	Figure A	30	_	_
Read low-level p	ulse width	PWLR	ns	Figure A	170	_	_
Write high-level p	oulse width	PW _{HW}	ns	Figure A	25	_	_
Read high-level p	oulse width	PWhr	ns	Figure A	250	_	_
Write / Read rise	/ fall time	twrr, wrf	ns	Figure A	_	-	25
Setup time	Write (RS to CSX, WRX)	— tas	ns	Figure A	0	_	_
	Read (RS to CSX, RDX)	— IAS	ns	Figure A	10	_	-
Address hold tim	e	tан	ns	Figure A	2	_	_
Write data setup	time	tosw	ns	Figure A	25	_	_
Write data hold ti	me	tн	ns	Figure A	10	_	_
Read data delay	time	toor	ns	Figure A	_	_	150
Read data hold ti	ime	tohr	ns	Figure A	5	_	_

Note: The above values are target values. They are subject to change.

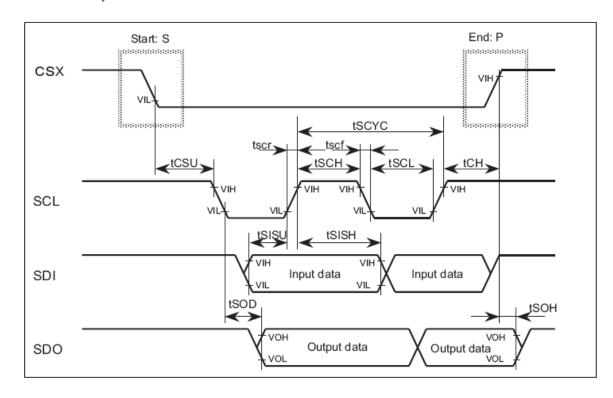
80-System Bus Interface Timing Characteristics (18-/16-bit Interface)

Table 103 (IOVCC=1.65V ~ 3.30V) (T.B.D.)

ltem		Symbol	Unit	Timing Diagram	Min.	Тур.	Max.
Bus cycle time	Write	tcycw	ns	Figure A	75	-	-
	Read	tcycr	ns	Figure A	450	-	-
Write low-level pu	lse width	PWLw	ns	Figure A	40	-	-
Read low-level pu	lse width	PWLR	ns	Figure A	170	-	-
Write high-level pu	ılse width	PWHW	ns	Figure A	25	-	-
Read high-level pu	ulse width	PWhR	ns	Figure A	250	-	-
Write / Read rise/	fall time	twr, wrf	ns	Figure A	-	-	25
Setup time	Write (RS to CSX, WRX)	4.0	ns	Figure A	0	-	-
	Read (RS to CSX, RDX)	— tas	ns	Figure A	10	-	-
Address hold time		tан	ns	Figure A	2	-	-
Write data setup ti	me	tosw	ns	Figure A	25	-	-
Write data hold tin	ne	tн	ns	Figure A	10	-	-
Read data delay ti	me	todr	ns	Figure A	-	-	150
Read data hold tin	ne	tohr	ns	Figure A	5	-	-
Note: The abo	ove values are tara	-4l The		.:			

Note: The above values are target values. They are subject to change.

Clock Synchronous Serial Interface



Clock Synchronous Serial Interface Timing Characteristics

Table 105 (IOVCC=1.65V ~ 3.30V) (T.B.D.)

ltem		Symbol	Unit	Timing Diagram	Min.	Тур.	Max.
Serial clock cycle	Write (receive)	tscyc	ns	Figure B	100	_	20,000
time	Read (transmit)	tscyc	ns	Figure B	350	_	20,000
Serial clock high-	Write (receive)	tscн	ns	Figure B	40	_	_
level width	Read (transmit)	tscн	ns	Figure B	150	_	_
Serial clock low-	Write (receive)	tscL	ns	Figure B	40	_	_
level width	Read (transmit)	tscL	ns	Figure B	150	_	_
Serial clock rise/fall	time	tscr, tscf	ns	Figure B	_	_	20
Chip select setup tin	ne	tcsu	ns	Figure B	20	_	_
Chip select hold time	е	tсн	ns	Figure B	60	_	_
Serial input data set	up time	tsısu	ns	Figure B	30	_	_
Serial input data hol	d time	tsish	ns	Figure B	30	_	_
Serial output data de	elay time	tsop	ns	Figure B	-	_	130
Serial output data ho	old time	tsон	ns	Figure B	5	_	_

Note: The above values are target values. They are subject to change.

7. PIN DESCRIPTION

Pin No.	Symbol	Description
1	NC	NC
2	LEDA	Backlight LED anode
3	LEDK1	Backlight LED cathode(K1)
5	LEDK2	Backlight LED cathode(K2)
	LEDK3	Backlight LED cathode(K3)
6	LEDK4	Backlight LED cathode(K4)
_ 7	IMO	Select the MPU system interface mode 8bit DB[17:10] 16bit DB[17:10], DB[8:1] SPI
8	IM1	IMO 1 0 0
9	IM2	IM1
10	/RESET	L: initialization is executed
11-18	DB[17:10]	Data bus
19-26	DB[8:1]	Data bus
27	SD0	SPI interface output pin
28	SDI	SPI interface input pin
29	/RD	180 system:Serves as a read signal and reads data at the low level
30	/WR/SCL	180 system:Serves as a write signal and writes data at the risong edge SPI Mode:Synchronizing clock signal in SPI mode
31	RS	L:Command;H:display data
32	/CS	L:Chip Selected H:Chip Unselected
33	VCC	I/O interface supply voltage
34	GND	Ground
35	VCI	Analog power supply voltage
36	NC	NC
37	NC	NC
38	NC	NC
39	NC	NC
40	NC	NC

8. INSTRUCTION DESCRIPTION

•R6	R61580 Instruction List	UCTION	n List								-								ŀ		Γ
Majo Sperindes	or category	Index	Minor category Command	IB15	IB14	IB13	Upper C	Code IB11	IB10	189	188	187	186	185	žΗ			181	180	Note	
- 80	Display Control	1 000	Index Decision Code Band	* VIMIDI[]]	* ALMIDITAL	* *	* ALMIDIÉAL	* * VTWIDT[3]	* * VTWID1[3]	* ALMIDIELLI	* YFWIDTED!	ID7	ID6	IDS	ID4	ID3	ID2	ID21	ID0		Т
_	_	5	(Default)	0	0	0	1	0		3	}	ş	<u>ئ</u>	}	ŧ	ş	3	0			1
	-	olh	Driver Output Control (Default)	0	0	0	0	0	WS 0	0	92	0	0	0	0	0	0	0	0		
		02h	LCD Driving Wave Control		on the second	-	-	-	-	00g	-	-		-		angumumimum.		-	[0]MN		
	1-	03h	Entry Mode	TRIREG	DFM		BGR		,			ORG	,	1,0(1)	[6]Q/I	VW		,			Г
	12	0.7%	Display Control 1		-		PTDE		-	-	BASEE	-		-	-	00		-			Τ
	I.	de	(Default)	0	0	0	T	0	0	1	_	0	0	†	0	0	0	0	0		T
	•	1000	(Default)	0	0	0	T		Ħ	П	+		0		0	Н	П	0	0		1
	<u>-</u>	460	Display Control 3	0	0		0	0	PTS[2] 0	PTS[1]	4	9	0	PTG 0	0	150(3)		130(1)	180[0]		
		0Ah	Display Control 4		-			-	-	-	-	-	-	-		FIMARKOE	PM[2]	FM[1]	PM[0]		Γ
		0Ch	External Display Interface Control 1	0	ENO[2]	[NO[1]	ENC[0]	-	-	-	- BW		-	DM(I)	DM(0)	-	Ħ	RIM[1]	RIM[0]		Τ
	I.	400	(Default)	0	0	0	0	0	0	0	O CHIND	0 EMPC7	DAPPER)	0 UMDUU	0 Uridina	O EMP[3]	O COMPA	0 Lijdrij	0 EMPER		T
	-1	000	(Default)	0	0	0	0	0	0	0	Н	H	0	H	0	H	0	0	0		1
	_	0Eh	VCOM Low Power Control (Default)	0			°	°	°	°	°			VEMCO	VEMIO		°	°	0		
		OFh B	External Display Interface Control 2			-									VSPL	HSPL		EPL	Tag		
*	Power Control	10h	Power Control 1	0					BTEZ	втбі	BT[0]			VP[]	AP[0]		DSTB				Т
	_10	4			0	•	0			o Giod	Ť	0	0	- Libour	- Locales	0	o Notice	o Cul	o Notice		T
				0	0	0	0	0	0	-	0	0	0	-	-	0	-	-	-		1
		42	Power Control 3 (Default)	0	0		VRH(0)	0	0	0	VOMR	- -		PSON	NON O	VRH[4]	VRH(3)	VRH(2)	VRH(ii)		
	r-	139	Power Control 4				VDV[4]	VDV[3]	VDV[2]	NDV[1]	[0]AQA										
5*	T	20h	(Default.) Frame Mercoy Asideas Set (Noticedal Address)	0	0	•				0	0	0 VD[2]	0 VD[0]	0 VD(8)	0 VD[4]	0 VD[3]	0 VD[2]	0 VD[i]	0 VD[0]		T
_	Access Control	_	(Default)	0	0	0	0	0	0	0		H	0	0	0	H	0	0	0		1
	-		Frame Mercery Address Set (Vertical Address) (Default)	0	0	•	0	0	0	0	VD[18]	AD(15)	AD[14]	0 0	AD[12]	VD[11]	O O		ND(8)		
	<u> </u>	22h	Frame Memory Data Write/Read					Frame memo	ry write data M	Frame memory write data WD[17.0] are transferred via different data bus in different interface	nsferred via dil	Terent data bu	us in different	interface opera	operations.						Г
z	NVM Write Control 2	28h	NVM Data Read 1	-		-		-	-	-	-	[2]01	(9)qr	[6]OI	[4]	[5]01	10(2)	(i)ai	[0]at		Τ
		20%		0	0	0	۰	0	-+-	0	0	+	- NOMITED	- NOW I'M	- Maria	- KONIGA	-	- NOW	- NOMIGO		T
		104		0	0	0	0	0	o	0	0	-	-	: 1		-	-	-	-		1
_		2Ah		0	0	۰		+-	+-		_	VCMSEL VCM2[6]	VCM2[6]	VCM2[5]	Т	+	VONZ[2]	VCMZ[1]	VCM2[0]		1
å	Gamma Control	30h	Gamma Control 1	c	e	e	+	PR0P01[3]	PR0P01[2]	PROPO([1]	PR0P01[0]	e			PRDP00[4]		PR0P00[2]	PROPOD[1]	PR0P00[0]		
	r'	31h	Germa Control 2	PR0P04[3]	PH0PO4[2]	PR0P04[1]	PR0P04(0)	PR0P03[3]	PR0P03[2]	PROPGG[1]	PR0P03[0]				PROPOZ(4)	PR0P02[3]	PR0P02[2]	PR0P02[1]	PR0P02[0]		Γ
	1	32h				,		PR0P06[3]		PROPOS(1) F	Н	-	H	H		PR0P05[3]	H0P05[2]	PR0P05[1]	PR0P05[0]		Τ
		ź		0	0	•		 -	0 PROPOR[2]		4		0		0 PROPOZÍA]	0 PROPOSITION P	0 (9000000	0	0 PROPOZÍO		T
		E00		0	0	0	0	+		4	0	0	0	+	Ħ	0	0	0	0		٦
		34h	Genma Control 5 (Default)	0	0	PIR0P3[1]	PIR0P3[0] 0	0	0	PIR0P2[1] 0	PIR0P2[0] 0			0	0	0	0	PPR0P0(1)	PIPOP0[0] 0		
	<u> </u>	35h		c	c	6	PRONO![4]	PRONO1[3]			PRON01[0]				H		PR0N00[2]	PRONOO[1]	PR0N00[0]		
	<u> </u>	36h	Gamma Control 7	PR0N04[3]	PRONOM[2]	PRONO4(1)			PRONOG[2]		PRON03[0]			-	PRDN02[4]	PR0N02[3]	PROMO2[2]	PRONO2[1]	PH0N02[0]		Π
	12	374	Gamma Control 8		•			PR0N06[3]	PRONO6[2]	PRONOS[1]	PRONOB[0]					PR0N05[3]	PR0N05[2]	PRONOS[1]	PR0N05[0]		T
	1"	389	(Default) Gamma Control 9	0	0	•	PRONOS[4]	- 1 - 3	PRONOB[2]	PRONOB(1)	0 PRON08(0)	•	0	+	DRONO7[4]	PROMO7[3]	0 PRON07[2]	PPON07[1]	0 PR0N07[0]		Т
	L.	386	(Default) Gamma Control 10	0	0	PIRON3[1]	O PSRON3[0]			PIRON2[1]	0 PIRON2[0]			PIRONI[1]	0 PIRON1[0]		0	PERONO[1]	0 PIRONO[0]		T
_		-	(Default)	0	0	0	0	0	0	H	0	0	0	H	0	0	+	0	0		T
6	_	_	fault)	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0		٦
	_	el s	Window Nertunetal Frame Monory Address (End Address) (Default)	0	0					0	+	HEADI	HEA(6)	HEAGG	HEAG	HEA3	t	HEAGI	HEA[0]		
	<u></u>	52h	Mindon Various France Memory Address (Start Address) (The Facility)	ď	e			c	ď	ď	VSA[8]	VSA(7)	VSA(6)	VSA[6]	VSA[4]	VSA[3]	VSA[2]	VSA[i]	VSA[0]		
		535	Worker Vertical Faces Money Advess End Address)								VEA[8]	VEA(7)	VEA(6)	VEA[5]	VEA[4]	VEA(3)	11	VEA[1]	VEA[0]		Τ
*9	Base Image	409	Driver Output Control	so		NL[6]	NLCO	M.O	NL(3)	NL[2]	NI(I)		,	SOME	SCN[4]	SCN(3)	SCN[2]	SON(1)	SCN[0]		Τ
		61h	Base Image Display Control						-							-	NDL	VSSON	INVON		Т
	-	6Ah	(Default) Vertical Scroll Control	0	0	0	0	0	0	0	VL(8)	WID.		WEB	0 VL[4]	o Di	W.[2]	VL[1]	VL[0]		Т
S& David	Partial Dienlay Control 80h	909	(Default) Partial Image Dienlay Bosition	0	0	L	0	0	0		H	4.	+	PTDP(S)	0 PTDP[4]		1	TT:	0 PTDP[0]		Τ
		_	(Default)	0	0	•	0	0	0	0	H	Щ.	╬	0	++	11	}- -}-	77	0		1
			(Default)	0	0	۰	0	0	0	0	+	0	┿	₩	H	77	++	0	0		П
		170	(Default)	0	0	0	۰	٥	0	0	0		۰	0	۰	0	۰	0	0		Т

	Panel Interface Control 1 (Default) Panel Interface Control 1-1	0	0	0	q	o o	0	0	DIMIO	o	a	0	RTN[4]	1	161	
	(Default) Panel Interface Control 2	0	О	0	a	О	NOME21	o NOMÍ!]	0 NOW[0]	G	o	О	0			e
ı	(Default)	0	0	0	0	0	H	0	-	0	o	0	0	1.1	0	0
	(Default)	0	0	0	g	0	0	0	0 O	0	0	0	0		0	0
Ì	Panel Interface Control 4 (Default)	0	0	0	0	0	0	0	0	0	0	0	0			
	Panel Interface Control 5 (Default)	0	0	0	0	0	0	0.00	0	0	0	RTNE[5]	RTNE[4]	RTNE[3]		RTME(2)
1	Panel Interface Control 5-1	0	0	0	0	0			9	0	0	0	0	SPCNE 3		3 SPCWE[2]
1	Panel Interface Control 6		0	0		0	NOWE[2]	NOWE[1]	[0]3MCN						-	
1	Panel Interface Control 7						VEGWE[2]	VEOWETII	VEGWE[0]			-				MOPE[2]
1	Panel Interface Control 8	0	0	0	0	0	0	0	0	0	0	D	0	0		SOTE[2]
1	(Default) Panel Interface Control 9	0	0	0	0	0	0	0	0	0	PCD[VH(2]	PCDIVH(1] F	PODIVH(0)	0		PCDIV([2]
1	NVM Control 1	0 0	0 0	0	0	0 0	0	0 0	0 0	o E o	- 0	[1]d0	0 000	0		0 0
1	NVM Control 2	[51](03)	Di)a)	(0)03	E0(12)	(11)03	[01]03	603	[D[3]	(00)	[9]03	[5]03	(D)(d)	ED(3)		ED(2)
	NVM Control 3	•	> 0								++	88	e.	HTV.RTL.[3].	4	RTY RT. [2] RTY RT.]
	NVM Control 4														LL	right of the
	Back Light Control 1	9	> 0			0	> 0		2 0		> 0	> 0		>	1 1	
1	Constant			•								Ħ	(4)	тичемо(3)	1	THREWO(2) THREWQ(1)
	(Default)	0	0	0	0	0	0	0	0	0	0	T	THREW1[4]	THREWISS		THREWILZI THREWILL
	(Default)	0	0	0	٥	0	0	0	o	0	T	ULMTW6(S) L		ULMTW8(3)	12	
	(Default)	0	0	0	۰	0	0	0	0	0	0	-	Н		v. F	
	(Default)	0	0	0	0	o	0	0	0	0	0			-	4	
	(Default)	0	0	0	0	0	0	0	0	0	0					
	(Default)	0	0	0	0	0	0	0	0	0	0	LLMTW1[S] L	L.MTWI[4]	***	33	LLMTW1[2] LLMTW1[1]
	(Default)	0	0	0	0	0	0	0	0	0	0	0	0	PITCHW3	2	PTCHW[2] PTCHW[1
	(Defailt)	9	0	0	0	c			0	0	0		1(4)	CGAPW[3]	8:	COAPM[2]
	(Defeate)													COEFK0[3] C	8	COEFWO[2] COEFWO[1
	(Default)		0				•				0	Ħ	COEFKI(4)	00EPK1[3] 0	8	COEFKI[2] COEFKI[1]
	(Default)	0	0	0	٥	0	0	0	0	TBLMW[7]		N(S)		TBLMM(3)	E:	LMIN(2) TBLMM(1)
	(Default)	0	0	0	٥	0	0	0	o	+	TER OF S	-	1	+	1	Troi oct
	(Default)	0	0	0	o o	0	0	0	0	+		1	0			0
	(Default)	0	0	0	0	0	0	0	0	TBL1[7]	TBL:[6]	TBL (5)	TBL 4	TBL/[3]	-:	TBL:1(2)
	(Default)	0	0	0	0	0	0	0	0	TBL 2(7)	TBL2[6]	TB1.2[5]	TBL2(4)	TBL2(3)	-:	TBL2[2]
	(Defeate)									18.30	TBL3[8]	78(3)3)	TBL3(4)	1813[3]	-	[2]E101
1	(Northern)	0	> 0	,		3 0			H	TBLACT	TBL4(6)	TBL4(5)	TBL4(4)	TBLA(3)		TBL4(2)
	(Default)	0	0	0	0	0		0	0	TBLSD1	TBLS[6]	TBLS[5]	T81.5[4]	TBL5[3]		TBLS(2)
	(Default)	0	0	0	0	0	0	0	0	TBL6(7)	TBL6[6]	0 TBL6[5]	0 TBUS(4)	0 TBL6(3)		TBU6[2]
	(Default)	0	0	0	0	0	0	0	0		0					
	(Default)	0	0	0	0	0	0	0	0	781-707	TBL7(6)	TBL/(5)	TBL7(4)	TBL7(3)	1.0	TBL7[2]
	Back Light Control 2 (Default)	0	0	0	9	0	0		9	0		0	0	9		0
	(Defects)									BDCV[7]	BDCV[6]	BDCV[5]	BDCV(4)	BDCV[3]	1 :	BDCv[2] BDCv[1]
	(Totalian)								Ħ	PWMD[7]	PWM05/[6]	H	PWMDIV[4]	PMMD(v(3)	11	PWMDIV[2] PSMDIV
1	(Default)	0	0	0		0	0	0	9		D.		W	LEDPWME : LI		LEDPWMPOL
	(Default)				•											

9. BACKLIGHT PARAMETERS

9.1 ABSOLUTE MAXIMUM RATINGS

(Unless specified, The Ambient temperature Ta=25°C)

Item	Symbol	Condition	Rating	Unit
Operating temperature range	Topr		-20~+70	⁰ C
Storage temperature range	Tst		-30~+80	⁰ C

9.2 ELECTRICAL/OPTLCAL CHARACTERISTICS

(Unless specified, The Ambient temperature Ta=25°C)

Item	Symbol	min	typ	max	Unit	Condition
Forward Voltage	Vf	3.0	3.2	3.4	V	If=60mA
Luminance	Lv	3000			cd/m ²	If=60mA
1 1'	X	0.26		0.30		IC (O A
color coordinate	Y	0.26		0.30		If=60 mA

10. Product Quality & Reliability

10.1 Standard for Quality Test

10.1.1 Inspection:

Before delivering, the supplier should take the following tests, and affirm the quality of product.

10.1.2 Electro-Optical Characteristics:

According to the individual specification to test the product.

10.1.3 Test of Appearance Characteristics:

According to the individual specification to test the product.

10.1.4 Test of Reliability Characteristics:

According to the definition of reliability on the specification for testing products.

10.1.5 Delivery Test:

Before delivering, the supplier should take the delivery test.

A. Test method: According to GB/2828, General Inspection Level take a single time.

B. The defects classify of AQL as following:

Major defect: AQL=0.25 Minor defect: AQL=1.0 Total defects: AQL=1.0

10.2 Standard for inspection

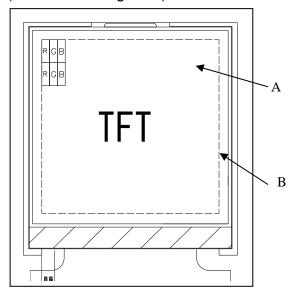
10.2.1 Manner of appearance test:

- a. The test must be under a 40W fluorescent light, and the distance of view must be at 30~35 cm.
- b. When test the model of transmissive product must add the reflective plate.
- c. The test direction is base on about around 45° of vertical line.

10.2.2 Definition of area: A B

A Area: Viewing area.

B Area: Out of viewing area. (Outside viewing area)



10.2.3 Basic principle:

- A. In principle the defect out of Area A should be acceptable if the defect does not affect assemblage and the quality of productions.
- B. If defects that can not describe clearly, acceptable samples will be the standard.
- C. The sample of the lowest acceptable quality level must be discussed by both supplier and customer when any dispute happened.
 - D. Must add new item on time when it is necessary.

10.2.4 Standard of inspection

Defect	Inspect item		(Criteria		
	Scratch and fold on polarizer.	1)	width ≤ 0.02	mm	length	ignore
	Scratch on glass.				acc	eptable
1	Glass fiber etc.	2)	0.02 mm <width< th=""><th>th≤0.05</th><th>mm</th><th></th></width<>	th≤0.05	mm	
Minor	(by bare eyes, defect outside A	leng	gth≤3 mm	tv	vo are acce	ptable
	area is acceptable)	3)	width>0.05 m	m		reject

Defect	Inspect item	Criteria
	Chip on glass(round type)	Φ≤0.1mm acceptable
	Chip on polarizer(round type)	0.1<Φ≤0.2mm two are acceptable
	Air bubble between polarizer	
2	and glass	1.The distance between any two dots should
Minor		be more than 5mm.
	a	2.Defect outside A area is acceptable.
	b +	3.If the air bubble is black, it can be judged
	$\Phi = (a + b)/2$	as black spot.

Defect	Inspect item	Criteria
3 Minor	x: length y: width z: thickness	x≤3 mm z≤t y≤1/3 s reject t: glass thickness. S: distance between glass edge and inside of edge sealing

Defect	Inspect item	Criteria
	Chip on corner of neat edge	x≤3 mm y≤3 mm z≤t
4 Minor	X: length Y: width	acceptable any chip exposes the silver dot reject
	X: length Y: width S: width of edge sealing	

Defect	Inspect item		Crite	ria
5 Minor	Chip on corner of terminal edge D D D T D	x<0.3 mm x≤3 mm	n or y<0.3 mm y <d< th=""><th>two are acceptable</th></d<>	two are acceptable

Defect	Inspect item	Criteria	
6 Minor	Chip on opposite side of terminal	a≥80mm , x≥7mm a<80mm , x>5mm y>1/2D z>1/2t , y>1/4D D: terminal length	reject reject reject reject

Defect	Inspect item	Criteria
	Cutting/breaking defect (flare)	According to the dimension of drawing
7		
Minor		

Defect	Inspect item	Criteria	
8 Minor	Crack	Any crack trend to extend	reject

Defect	Inspect item	Criteria
9	Liquid leakage, open sealant	reject
Major		

Defect	Inspect item	Criteria
10	Rainbow	According to samples
Minor		

Defect	Inspect item		Criteria
11	FPC, TCP, FLEX are broken or		reject
Major	not connected firmly		

Defect	Inspect item	Criteria
	The component on PCB or FPC	reject
12	is missing ,soldered unfirmly or	
Minor	bridged	

Defect	Inspect item	Criteria	
12	The soldering tin is not enough	The height that soldering tin covers	the
13		bump of component is 1/2 less than	the
Minor		height of bump reject	

Defect	Inspect item			Cr	iteria		
14	The soldering tin overflows	The	soldering	tin	covers	whole	bump
Minor						reject	

Defect	Inspect item	Criteria
15	The component is broken	reject
Minor		

Defect	Inspect item	Criteria	
16	The shape of pinouts is not the	It makes the LCM work badly	reject
Minor	same as that in the criterion		

Defect	Inspect item		Criteria
17	The pinout is broken		reject
Minor			

Defect	Inspect item			Criteria	
18	The frame is scratched visibly	Length			ignore
Minor		Width	>0.5mm		reject

Defect		Inspect	item		Criteria
	The	frame	is	rusted	When the shape is as dot, reference
19	(accum	ulation)			to defect 23
Minor					When the shape is as line,reference
					to defect 24

Defect	Inspect item		Cri	teria
	Scratch and fold on touchpanel.		1) width≤0.02 mm	acceptable
20	(by bare eyes ,defect outside A		2) 0.02 mm <width≤0.< th=""><th>05 mm</th></width≤0.<>	05 mm
Minor	area is acceptable)		length≤5 mm	two are acceptable
			3) width>0.05 mm	reject

Defect	Inspect item	Criteria
	Black & white dots on	1) Φ≤0.1 mm acceptable
	touchpanel (round type)	2) 0.1<Φ≤0.3 mm three are acceptable
	Air bubble on touchpanel	3) Ф>0.3 mm reject
21		1.The distance between any two dots should
Minor	Minor $\Phi=(a+b)/2$	be more than 5mm.
		2.Defect outside A area is acceptable.
		3.If the air bubble is black, it can be judged
	——	as black spot.

Defect	Inspect item	Criteria
22	Touchpanel warps	According to the dimension of drawing.
Minor		

Defect	Inspect item	Criteria
23	Dirty on rear of touchpanel	It's visible at condition of 30±5 cm, 45°
Minor		

10.3 RELIABILITY

Item	Condition	Criterion	
High temperature	70°C , 96 hrs	-Cosmetic defects are not allowed	
operation		after the test(Polarizer change is	
Low temperature	-20°C , 96 hrs	exceptional)	
operation		-Contrast ratio change over 50% of initial value should not be happened -The current consumption should be below double of initial value -Brightness decrease should be lower than 50% of initial value	
Moisture storage	60°C , 90%RH, 96 hrs		
High temperature storage	80°C , 96 hrs		
Low temperature storage	-30°C , 96 hrs		
Thermal shock	-30°C (30 minute)		
	25°C (5 minute)		
	80°C (30 minute)		
	CYCLES: 10		
LIFE TIME	50,000 hours, 25±10°C,		
	45±20% RH		

11. PRECAUTIONS IN USING

11.1 Liquid crystal display (LCD)

The LCD panel is made up of glass, organic fluid and polarizer. When handling, please pay attention to the following items:

- 1) Keep the operation and storage temperature of the LCD within the range specified in the LCD specification. Otherwise, excessive temperature and humidity would cause polarization degradation, bubble generation or polarizer peel-off.
- 2) Prevent it from mechanical shock by dropping it from a high place, etc.
- 3) Don't contact, push or rub the exposed polarizers with anything harder than HB pencil lead.
- 4) Avoid using chemicals such as acetone, toluene, ethanol and isoropylalcohol to clean the front/rear polarizers and reflectors, which will cause damage to them.
- 5) Wipe off saliva or water drops immediately. Contact with water over a long period of time may cause deformation or color fading. The LCM is assembled and adjusted with a high degree of precision.
- 6) Do not put or attach anything on the display area. Avoid touching the display area with bare hand.

11.2 Precaution for handling LCD modules

The LCM is assembled and adjusted with a high degree of precision, do not applying excessive shocks to it or making any alterations or modifications to it, the following precautions should be taken when handing.

- 1) Do not drop, bend or twist the module.
- 2) Do not alter or making any modification on the shape of the metal frame.
- 3) Do not change the shape, the pattern wiring or add any extra hole on the PCB.
- 4) Do not modify or touch the zebra rubber strip(conductive rubber) with another object.
- 5) Do not change the positions of components on the PCB.

11.3 Eletro-static discharge control

Careful attention should be paid to control the electrostatic discharge of the modules, since the modules contain no. of CMOS LSI.

- 1) Make sure you are grounded properly when remove the module from its antistatic bag. Be sure that the module and have the same electric potential.
- 2) Only properly grounded soldering iron should be used.
- 3) Modules should be stored in antistatic bag or other containers resistant to static after remove from its original package.
- 4) When using the electric screw-driver is used, make sure the screw driver had been ground potentiality to minimize the transmission of EM wave produced by commutator sparks.
- 5) In order to reduce the generation of static electricity, a relative humidity of 50-60% is recommended.

11.4 Precaution for soldering

- 1) Soldering should apply to I/O terminals only.
- 2) Soldering temperature is 280°C+(-)10°C.
- 3) Soldering time 3-4 seconds.
- 4) Eutectic solder (rosin flux filled) should be used.
- 5) If soldering flux is used, be sure to remove any remaining flux after finishing the soldering operation and LCD surface should be covered during soldering to prevent any damage to flux spatters.
- 6) When remove the lead wires from the I/O terminals, use proper de-soldering methods, e.g. suction type de-soldering irons. Do not repeat wiring by soldering more than three times at the pads and plated though holes may be damaged.

11.5 Precaution for operation

- 1) Adjust liquid crystal driving voltage (Vo) to varies viewing angle and obtain the contrast.
- 2) Vo should be kept in proper range stated in the specification. Excess voltage will shorten the LCD life.
- 3) Response time is greatly delayed at low temperature. It will recover when go back to normal temperature.
- 4) Condensation on terminals can cause an electrochemical reaction disrupting the terminal circuit. Therefore it should be used under the relative condition of 50% RH.

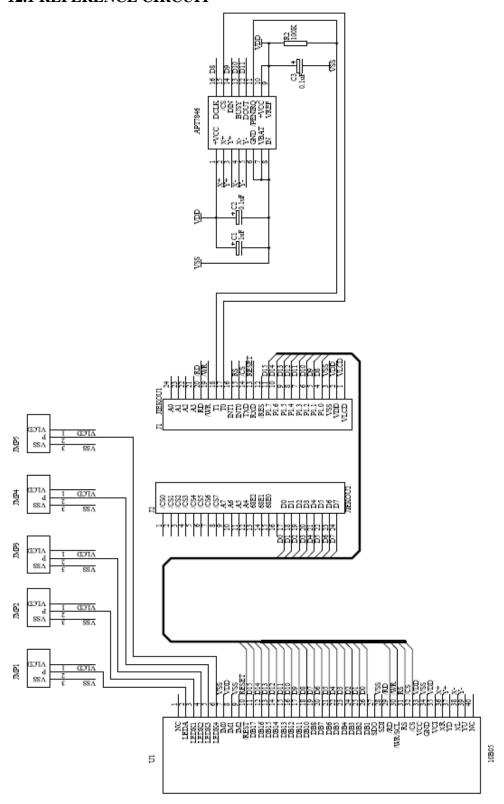
11.6 Storage

When long term storage is required, following precautions are necessary:

- 1) Storage them in a sealed polyethylene bag (antistatic), seal the opening, and store it where it is not subjected to direct sunshine, or to the light of fluorescent lamp. If properly sealed, there is no need for desiccant.
- 2) Store them in the temperature range of -30°C~80°C and at low humidity is recommended.

12. APPLICATION

12.1 REFERENCE CIRCUIT



12.2 APPENDIX

INITIALIZATION FOR REFERENCE (MPU: AT89C512):

```
void LCD_Init()
LCD_CtrlWrite(0x00);LCD_DataWrite(0x0000);
LCD_CtrlWrite(0x00);LCD_DataWrite(0x0000);
delay(100);
LCD_CtrlWrite(0x00);LCD_DataWrite(0x0000);
LCD_CtrlWrite(0x00);LCD_DataWrite(0x0000);
LCD_CtrlWrite(0x00);LCD_DataWrite(0x0000);
LCD_CtrlWrite(0x00);LCD_DataWrite(0x0000);
LCD_CtrlWrite(0xA4);LCD_DataWrite(0x0001);
delay(100);
LCD CtrlWrite(0x60);LCD DataWrite(0xA700);
LCD_CtrlWrite(0x08);LCD_DataWrite(0x0808);
//Gamma Setting:
LCD_CtrlWrite(0x30);LCD_DataWrite(0x0203);
LCD_CtrlWrite(0x31);LCD_DataWrite(0x080F);
LCD_CtrlWrite(0x32);LCD_DataWrite(0x0401);
LCD_CtrlWrite(0x33);LCD_DataWrite(0x050B);
LCD_CtrlWrite(0x34);LCD_DataWrite(0x3330);
LCD_CtrlWrite(0x35);LCD_DataWrite(0x0B05);
LCD_CtrlWrite(0x36);LCD_DataWrite(0x0005);
LCD_CtrlWrite(0x37);LCD_DataWrite(0x0F08);
LCD_CtrlWrite(0x38);LCD_DataWrite(0x0302);
LCD_CtrlWrite(0x39);LCD_DataWrite(0x3033);
//Power Setting:
LCD_CtrlWrite(0x90);LCD_DataWrite(0x0018);//80Hz
LCD_CtrlWrite(0x10);LCD_DataWrite(0x0530);//BT,AP
LCD_CtrlWrite(0x11);LCD_DataWrite(0x0237);//DC1,DC0,VC
LCD_CtrlWrite(0x12);LCD_DataWrite(0x01BF);
LCD_CtrlWrite(0x13);LCD_DataWrite(0x1000);//VCOM
delay(200);
/***************
LCD_CtrlWrite(0x01);LCD_DataWrite(0x0100);
LCD_CtrlWrite(0x02);LCD_DataWrite(0x0200);
LCD_CtrlWrite(0x03);LCD_DataWrite(0x1030);
LCD CtrlWrite(0x09);LCD DataWrite(0x0001);
LCD_CtrlWrite(0x0A);LCD_DataWrite(0x0008);
LCD_CtrlWrite(0x0C);LCD_DataWrite(0x0000);
LCD_CtrlWrite(0x0D);LCD_DataWrite(0xD000);
LCD_CtrlWrite(0x0E);LCD_DataWrite(0x0030);
LCD_CtrlWrite(0x0F);LCD_DataWrite(0x0000);
LCD_CtrlWrite(0x20);LCD_DataWrite(0x0000);//H Start
LCD_CtrlWrite(0x21);LCD_DataWrite(0x0000);//V Start
LCD_CtrlWrite(0x29);LCD_DataWrite(0x002E);
LCD_CtrlWrite(0x50);LCD_DataWrite(0x0000);
LCD_CtrlWrite(0x51);LCD_DataWrite(0x00EF);
LCD_CtrlWrite(0x52);LCD_DataWrite(0x0000);
LCD_CtrlWrite(0x53);LCD_DataWrite(0x013F);
LCD_CtrlWrite(0x61);LCD_DataWrite(0x0001);
LCD_CtrlWrite(0x6A);LCD_DataWrite(0x0000);
LCD_CtrlWrite(0x80);LCD_DataWrite(0x0000);
LCD_CtrlWrite(0x81);LCD_DataWrite(0x0000);
LCD_CtrlWrite(0x82);LCD_DataWrite(0x005F);
LCD_CtrlWrite(0x93);LCD_DataWrite(0x0701);
 ***************
LCD_CtrlWrite(0x07);LCD_DataWrite(0x0100);
delay(100);
```